

XP02501 (XP2501)

Silicon NPN epitaxial planar type

For general amplification

■ Features

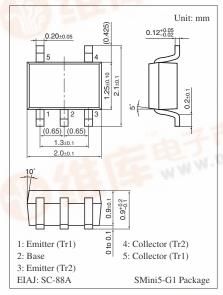
- Two elements incorporated into one package (Base-coupled transistors)
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

• 2SD0601A (2SD601A) × 2

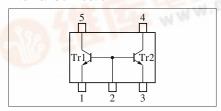
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	60	V
Collector-emitter voltage (Base open)	V_{CEO}	50	V
Emitter-base voltage (Collector open)	V_{EBO}	7	V
Collector current	I_C	100	mA
Peak collector current	I_{CP}	200	mA
Total power dissipation	P_{T}	150	mW
Junction temperature	T_{j}	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Marking Symbol: 5W

Internal Connection



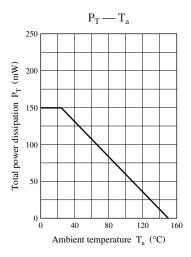
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

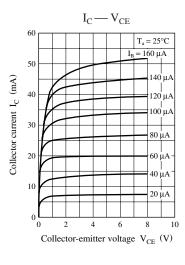
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \ \mu A, I_E = 0$	60		100	V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	50		218	V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \ \mu A, I_C = 0$	7		- 4	V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 10 \text{ V}, I_{B} = 0$			100	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$	160		460	_
h _{FE} ratio *	h _{FE(Small/} Large)	$V_{CE} = 10 \text{ V}, I_{C} = 2 \text{ mA}$	0.50	0.99		_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 100 \text{ mA}, I_B = 10 \text{ mA}$		0.1	0.3	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_{E} = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		3.5		pF

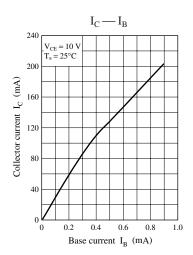
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

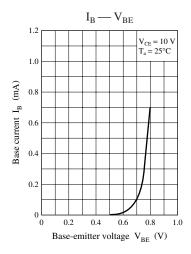
Ratio between 2 elements

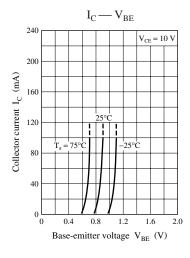
XP02501 Panasonic

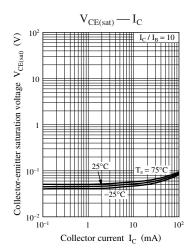


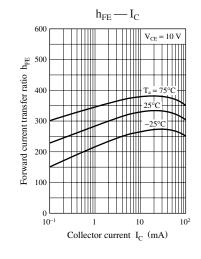


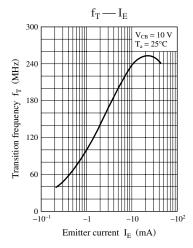


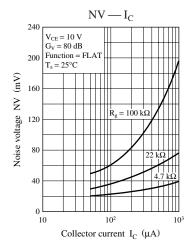












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